



Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
------------	--	---------------------------	--

Supplier Information

Company Name * STMicroelectronics	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *	<input type="button" value="Duplicate Contact -> Authorized Representative"/>				
Authorized Representative * Emilio Castelli	Title - Representative APG Material Declaration Cham	Phone - Representative *	Email - Representative *	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	L5300AH7	A695*UN41AA6	2011-01-18	A	SH1A	290	mg	Each
Alternate Recommendation	TO-252 6 LEADS SDM (HPAK)			Alternate Item Comments	Internal ST reference: BSA: CD00263648 EcoPack1			

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Tin (Sn)	CU Alloy	3	260 C	30 seconds	3

Comments

Disclaimer: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Clear all of the fields on this form

Reset Form

Lock the fields on this form to prevent changes

Lock Supplier Fields

RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive 2002/95/EC **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance *

Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

+ - 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

+I	-I	Item/SubItem Name	+M	-M	Homogeneous Material	Weight	Unit of Measure	+C	-C	Level	Substance Category	+S	-S	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
		TO-252 6 Leads SD			Integrated circuit	2.73	mg			Supplier	Silicon die			Silicon (Si)	7440-21-3		2.691	mg			985,71
											die metallization			Aluminium (Al)	7429-90-5		0.001	mg			366
											die metallization			Copper (Cu)	7440-50-8		0.001	mg			366
											die metallization			Titanium (Ti)	7440-32-6		0.001	mg			366
											die metallization			Chromium (Cr)	7440-47-3		0.002	mg			733
											die metallization			Gold (Au)	7440-57-5		0.004	mg			1,465
											die metallization			Nickel (Ni)	7440-02-0		0.012	mg			4,396
											die metallization			Vanadium (V)	7440-62-2		0.001	mg			366
											Die coating			Gamma-butyrolactone	96-48-0		0.012	mg			4,396
											Die coating			Polyhydroxyamide	55295-98-2		0.005	mg			1,832
					Leadframe	197.545	mg			supplier	frame alloy			Copper (Cu)	7440-50-8		196.919	mg			996,83
											frame alloy			Iron (Fe)	7439-89-6		0.091	mg			461
											frame alloy			Iron Phosphide (FeP)	26508-33-8		0.166	mg			840
											frame coating			Silver (Ag)	7440-22-4		0.269	mg			1,362
										B	frame coating			Nickel (Ni)	7440-02-0		0.1	mg			506
					Die Attach	1.879	mg			A	soft solder			Lead (Pb)	7439-92-1	7a. Lead	1.794	mg			954,76
										supplier	soft solder			Silver (Ag)	7440-22-4		0.047	mg			25,013
											soft solder			Tin (Sn)	7440-31-5		0.038	mg			20,224
					Bonding wire	0.452	mg			Supplier	Bonding wire			Gold (Au)	7440-57-5		0.452	mg			1,000,0
					Encapsulation	81.31	mg			supplier	Moulding Compound			Silica, vitreous	60676-86-0		65.047	mg			799,98
											Moulding Compound			Epoxy Cresol Novolak	29690-82-2		5.692	mg			70,004
											Moulding Compound			Phenol resin	9003-35-4		3.252	mg			39,995
											Moulding Compound			Biphenyl epoxy resin	85954-11-6		4.879	mg			60,005

					+C	-C	B	Moulding Compound	+S	-S	Antimony Trioxide	1309-64-4		0.976	mg			12,003
					+C	-C	B	Moulding Compound	+S	-S	Brominated Epoxy Resin	40039-93-8		1.22	mg			15,004
					+C	-C	supplier	Moulding Compound	+S	-S	Carbon Black	1333-86-4		0.244	mg			3,001
+M	-M	Finishing	6.084	mg	+C	-C	supplier	connection coating	+S	-S	Tin (Sn)	7440-31-5		6.084	mg			1,000,0